14A, 50V, 0.100 Ohm, Logic Level, N-Channel Power MOSFETs

These are N-channel power MOSFETs manufactured using the MegaFET process. This process, which uses feature sizes approaching those of LSI integrated circuits, gives optimum utilization of silicon, resulting in outstanding performance. They were designed for use in applications such as switching regulators, switching converters, motor drivers and relay drivers. This performance is accomplished through a special gate oxide design which provides full rated conductance at gate bias in the 3V-5V range, thereby facilitating true on-off power control directly from logic level (5V) integrated circuits.

Formerly developmental type TA09870.

Ordering Information

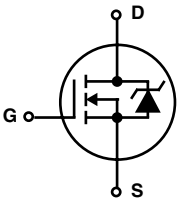
PART NUMBER	PACKAGE	BRAND
RFD14N05L	TO-251AA	14N05L
RFD14N05LSM	TO-252AA	14N05L
RFP14N05L	TO-220AB	FP14N05L

NOTE: When ordering, use the entire part number. Add the suffix 9A to obtain the TO-252AA variant in the tape and reel, i.e., RFD14N05LSM9A.

Features

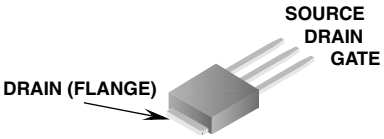
- 14A, 50V
- $r_{DS(ON)} = 0.100\Omega$
- Temperature Compensating PSPICE® Model
- Can be Driven Directly from CMOS, NMOS, and TTL Circuits
- Peak Current vs Pulse Width Curve
- UIS Rating Curve
- 175°C Operating Temperature
- Related Literature
  - TB334 “Guidelines for Soldering Surface Mount Components to PC Boards”

Symbol

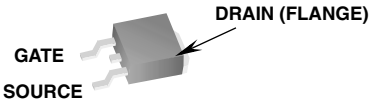


Packaging

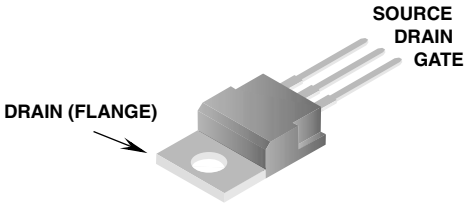
JEDEC TO-251AA



JEDEC TO-252AA



JEDEC TO-220AB



Absolute Maximum Ratings $T_C = 25^oC$, Unless Otherwise Specified

		RFD14N05L, RFD14N05LSM, RFP14N05L	UNITS
Drain to Source Voltage (Note 1)	V_{DSS}	50	V
Drain to Gate Voltage (R_{GS} = 20kΩ) (Note 1)	V_{DGR}	50	V
Gate to Source Voltage	V_{GS}	±10	V
Continuous Drain Current	I_D	14	A
Pulsed Drain Current (Note 3)	I_{DM}	Refer to Peak Current Curve	
Pulsed Avalanche Rating	E_{AS}	Refer to UIS Curve	
Power Dissipation	P_D	48	W
Derate above 25^oC		0.32	$W/^oC$
Operating and Storage Temperature	T_J, T_{STG}	-55 to 175	^oC
Maximum Temperature for Soldering			
Leads at 0.063in (1.6mm) from Case for 10s	T_L	300	^oC
Package Body for 10s, See Techbrief 334	T_{pkg}	260	^oC

CAUTION: Stresses above those listed in "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress only rating and operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied.

NOTE:

1. $T_J = 25^oC$ to 150^oC.

Electrical Specifications $T_C = 25^oC$, Unless Otherwise Specified

PARAMETER	SYMBOL	TEST CONDITIONS		MIN	TYP	MAX	UNITS
Drain to Source Breakdown Voltage	BV_{DSS}	I_D = 250μA, V_{GS} = 0V, Figure 13		50	-	-	V
Gate Threshold Voltage	$V_{GS(TH)}$	$V_{GS} = V_{DS}$, I_D = 250μA, Figure12		1	-	2	V
Zero Gate Voltage Drain Current	I_{DSS}	V_{DS} = 40V, V_{GS} = 0V		-	-	1	μA
		V_{DS} = 40V, V_{GS} = 0V, $T_C = 150^oC$		-	-	50	μA
Gate to Source Leakage Current	I_{GSS}	V_{GS} = ±10V		-	-	±100	nA
Drain to Source On Resistance (Note 2)	$r_{DS(ON)}$	I_D = 14A, V_{GS} = 5V, Figures 9, 11		-	-	0.100	Ω
Turn-On Time	$t_{(ON)}$	V_{DD} = 25V, I_D = 7A, R_L = 3.57Ω, V_{GS} = 5V, R_{GS} = 0.6Ω		-	-	60	ns
Turn-On Delay Time	$t_{d(ON)}$			-	13	-	ns
Rise Time	t_r			-	24	-	ns
Turn-Off Delay Time	$t_{d(OFF)}$			-	42	-	ns
Fall Time	t_f			-	16	-	ns
Turn-Off Time	$t_{(OFF)}$			-	-	100	ns
Total Gate Charge	$Q_{g(TOT)}$	V_{GS} = 0V to 10V	V_{DD} = 40V, I_D = 14A, R_L = 2.86Ω Figures 20, 21	-	-	40	nC
Gate Charge at 5V	$Q_{g(5)}$	V_{GS} = 0V to 5V		-	-	25	nC
Threshold Gate Charge	$Q_{g(TH)}$	V_{GS} = 0V to 1V		-	-	1.5	nC
Input Capacitance	C_{ISS}	V_{DS} = 25V, V_{GS} = 0V, f = 1MHz Figure 14		-	670	-	pF
Output Capacitance	C_{OSS}			-	185	-	pF
Reverse Transfer Capacitance	C_{RSS}			-	50	-	pF
Thermal Resistance Junction to Case	$R_{\theta JC}$			-	-	3.125	$^oC/W$
Thermal Resistance Junction to Ambient	$R_{\theta JA}$	TO-251 and TO-252		-	-	100	$^oC/W$
	$R_{\theta JA}$	TO-220		-	-	80	$^oC/W$

Source to Drain Diode Specifications

PARAMETER	SYMBOL	TEST CONDITIONS	MIN	TYP	MAX	UNITS
Source to Drain Diode Voltage (Note 2)	V_{SD}	I_{SD} = 14A	-	-	1.5	V
Diode Reverse Recovery Time	t_{rr}	I_{SD} = 14A, dI_{SD}/dt = 100A/μs	-	-	125	ns

NOTES:

2. Pulse Test: Pulse Width ≤ 300ms, Duty Cycle ≤ 2%.
3. Repetitive Rating: Pulse Width limited by max junction temperature. See Transient Thermal Impedance Curve (Figure 3) and Peak Current Capability Curve (Figure 5).

Typical Performance Curves Unless Otherwise Specified

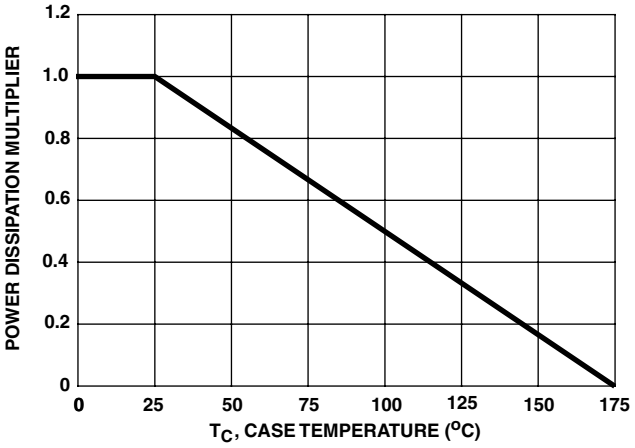


FIGURE 1. NORMALIZED POWER DISSIPATION vs CASE TEMPERATURE

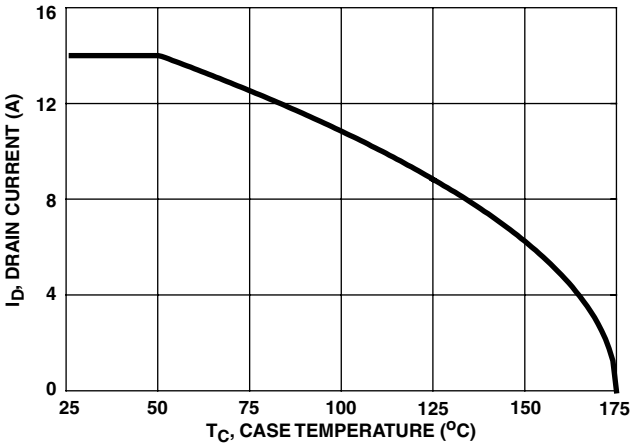


FIGURE 2. MAXIMUM CONTINUOUS DRAIN CURRENT vs TEMPERATURE

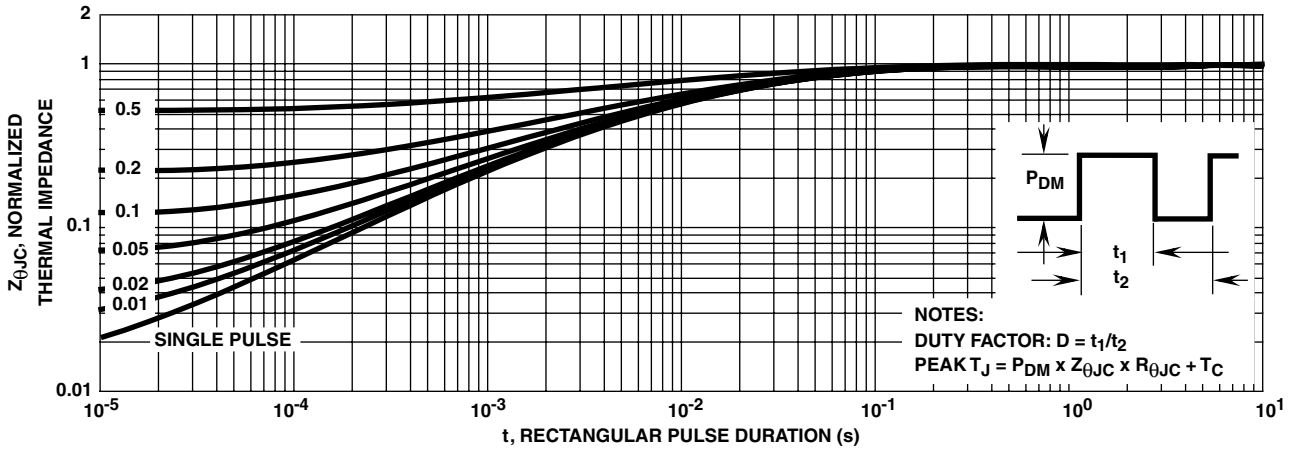


FIGURE 3. NORMALIZED MAXIMUM TRANSIENT THERMAL IMPEDANCE

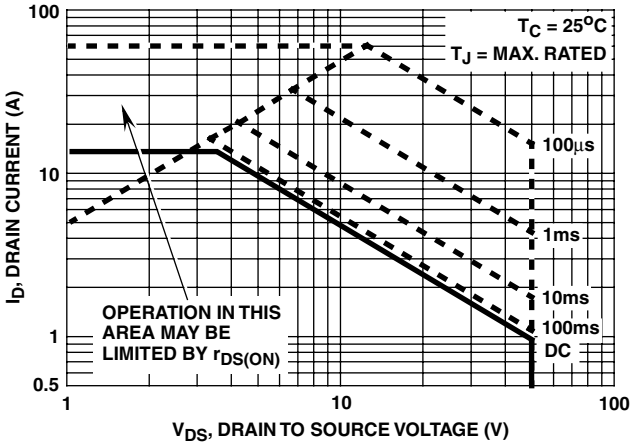


FIGURE 4. FORWARD BIAS SAFE OPERATING AREA

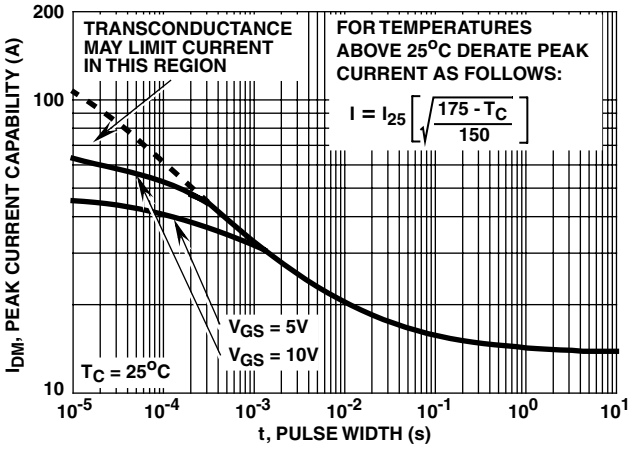


FIGURE 5. PEAK CURRENT CAPABILITY